

**P-Channel Enhancement Mode Power MOSFET**

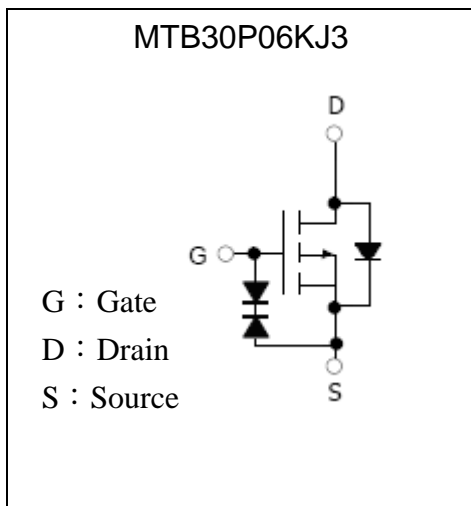
# MTB30P06KJ3

<b><math>BV_{DSS}</math></b>	<b>-60V</b>
<b><math>I_D @ V_{GS} = -10V, T_C = 25^\circ C</math></b>	<b>-23.6A</b>
<b><math>R_{DS(ON)} @ V_{GS} = -10V, I_D = -6A</math></b>	<b>23mΩ (typ)</b>
<b><math>R_{DS(ON)} @ V_{GS} = -4.5V, I_D = -4A</math></b>	<b>37mΩ (typ)</b>
<b><math>R_{DS(ON)} @ V_{GS} = -4V, I_D = -3A</math></b>	<b>44mΩ (typ)</b>

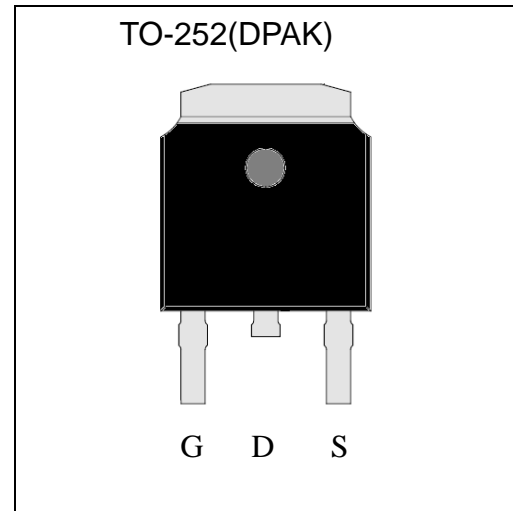
**Features**

- Low Gate Charge
- Simple Drive Requirement
- ESD Protected Gate
- Pb-free Lead Plating & Halogen-free Package

**Equivalent Circuit**

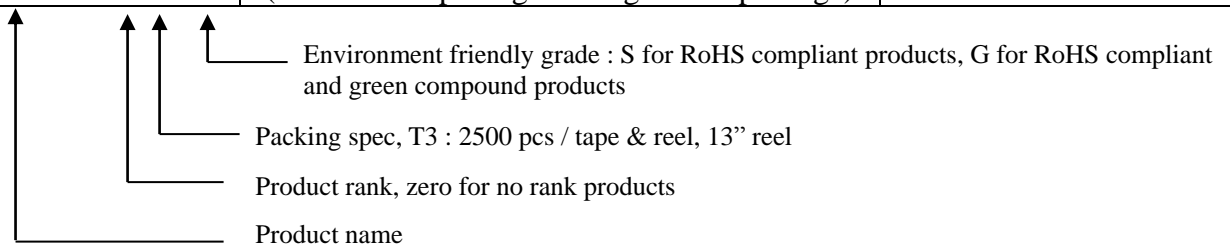


**Outline**



**Ordering Information**

Device	Package	Shipping
MTB30P06KJ3-0-T3-G	TO-252 (Pb-free lead plating & halogen-free package)	2500 pcs / Tape & Reel



**Absolute Maximum Ratings** ( $T_C=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Limits	Unit	
Drain-Source Voltage	$V_{DS}$	-60	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current @ $T_J=175^\circ\text{C}$ , $T_C=25^\circ\text{C}$ , $V_{GS}=-10\text{V}$ (Note 1)	$I_D$	-23.6	A	
Continuous Drain Current @ $T_J=175^\circ\text{C}$ , $T_C=100^\circ\text{C}$ , $V_{GS}=-10\text{V}$ (Note 1)		-16.7		
Continuous Drain Current @ $T_A=25^\circ\text{C}$ , $V_{GS}=-10\text{V}$ (Note 2)	$I_{DSM}$	-6.7		
Continuous Drain Current @ $T_A=70^\circ\text{C}$ , $V_{GS}=-10\text{V}$ (Note 2)		-5.4		
Pulsed Drain Current (Note 3)	$I_{DM}$	-94		
Avalanche Current (Note 3)	$I_{AS}$	-23.6		
Avalanche Energy @ $L=0.5\text{mH}$ , $I_D=-23.6\text{A}$ , $V_{DD}=-30\text{V}$ (Note 2)	$E_{AS}$	139	mJ	
Total Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$ (Note 1)	42	W
		$T_C=100^\circ\text{C}$ (Note 1)	21	
	$P_{DSM}$	$T_A=25^\circ\text{C}$ (Note 2)	2.5	
		$T_A=70^\circ\text{C}$ (Note 2)	1.6	
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	-55~+175	$^\circ\text{C}$	

\* 100% UIS testing in condition of  $V_D=-15\text{V}$ ,  $L=0.5\text{mH}$ ,  $V_G=10\text{V}$ ,  $I_{AS}=-12\text{A}$ , Rated  $V_{DS}=-60\text{V}$

**Thermal Data**

Parameter	Symbol	Typical	Maximum	Unit
Thermal Resistance, Junction-to-case	$R_{\theta JC}$	2.7	3.6	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-ambient, $t \leq 10\text{s}$ (Note 2)	$R_{\theta JA}$	15	18	
Thermal Resistance, Junction-to-ambient, steady state		40	50	

- Note : 1. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=175^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
2. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2 oz. copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The power dissipation  $P_{DSM}$  is based on  $R_{\theta JA}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
3. Pulse width limited by junction temperature  $T_{J(\text{MAX})}=175^\circ\text{C}$ . Ratings are based on low frequency and low duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

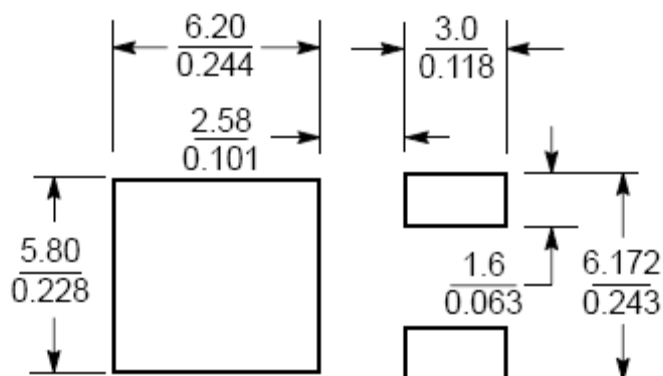
**Characteristics (Tc=25°C, unless otherwise specified)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
BV <sub>DSS</sub>	-60	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA
V <sub>GS(th)</sub>	-1.5	-	-2.5		V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA
I <sub>GSS</sub>	-	-	±10	μA	V <sub>GS</sub> =±16V, V <sub>DS</sub> =0V
I <sub>DSS</sub>	-	-	-1		V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V
	-	-	-25		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C
R <sub>DS(ON)</sub> *1	-	23	30	mΩ	V <sub>GS</sub> =-10V, I <sub>D</sub> =-6A
	-	37	48		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A
	-	44	57		V <sub>GS</sub> =-4 V, I <sub>D</sub> =-3A
G <sub>FS</sub> *1	-	15	-	S	V <sub>DS</sub> =-5V, I <sub>D</sub> =-6A
<b>Dynamic</b>					
Q <sub>g</sub> *1, 2	-	31.9	47.9	nC	I <sub>D</sub> =-23A, V <sub>DS</sub> =-48V, V <sub>GS</sub> =-10V
Q <sub>gs</sub> *1, 2	-	4.4	-		
Q <sub>gd</sub> *1, 2	-	13	-		
t <sub>d(ON)</sub> *1, 2	-	14.2	21.3	ns	V <sub>DS</sub> =-30V, I <sub>D</sub> =-1A, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω
t <sub>r</sub> *1, 2	-	19	28.5		
t <sub>d(OFF)</sub> *1, 2	-	55.4	83.1		
t <sub>f</sub> *1, 2	-	34.6	51.9		
C <sub>iss</sub>	-	1430	-	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =-25V, f=1MHz
C <sub>oss</sub>	-	206	-		
C <sub>rss</sub>	-	121	-		
R <sub>g</sub>	-	4	-	Ω	f=1MHz
<b>Source-Drain Diode Ratings and Characteristics</b>					
I <sub>S</sub> *1	-	-	-23.6	A	
I <sub>SM</sub> *1	-	-	-94		
V <sub>SD</sub> *1	-	-0.78	-1.2	V	I <sub>S</sub> =-6A, V <sub>GS</sub> =0V
t <sub>rr</sub>	-	11	16.5	ns	I <sub>F</sub> =-23A, dI <sub>F</sub> /dt=100A/μs
Q <sub>rr</sub>	-	5	-	nC	

Note : \*1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

\*2.Independent of operating temperature

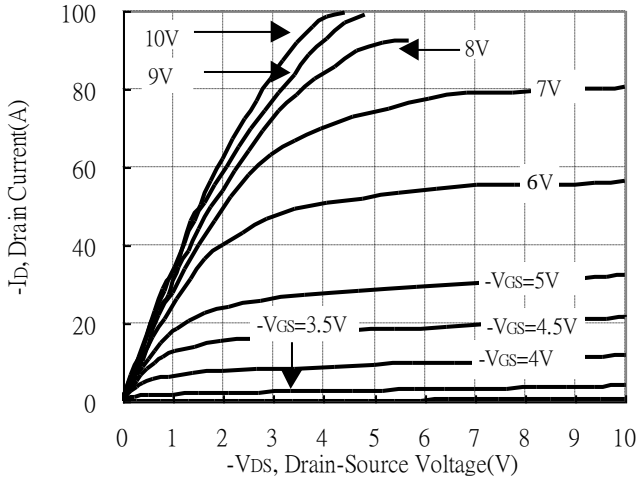
\*3.Pulse width limited by maximum junction temperature.

**Recommended soldering footprint**

 Unit (  $\frac{\text{mm}}{\text{inch}}$  )

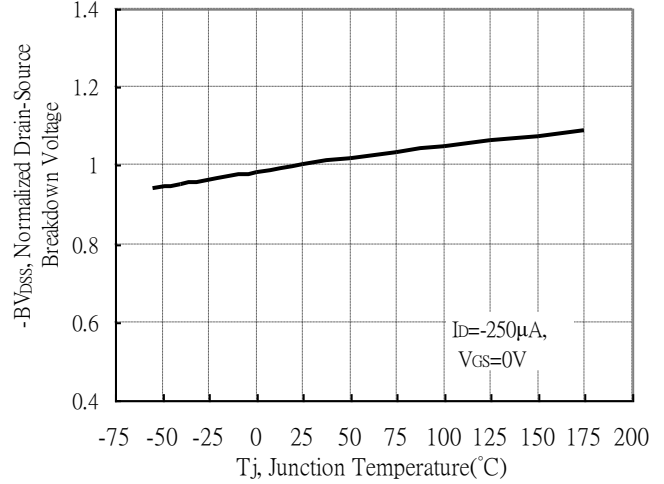


**Typical Characteristics**

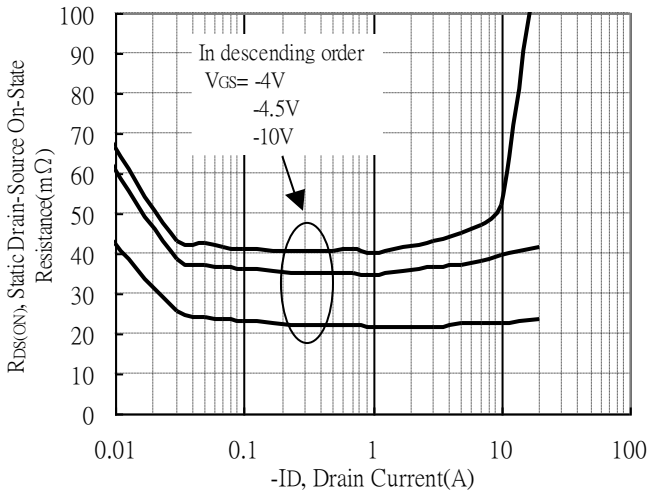
Typical Output Characteristics



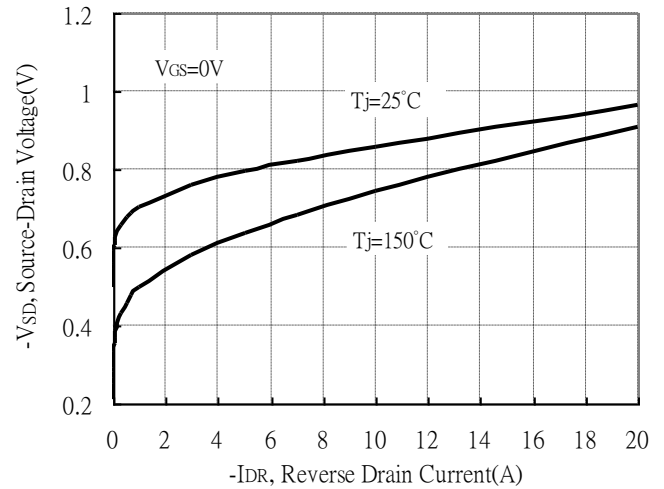
Brekdown Voltage vs Ambient Temperature



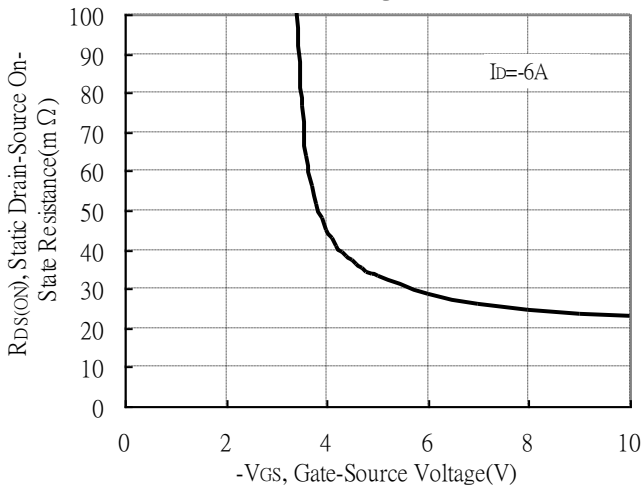
Static Drain-Source On-State resistance vs Drain Current



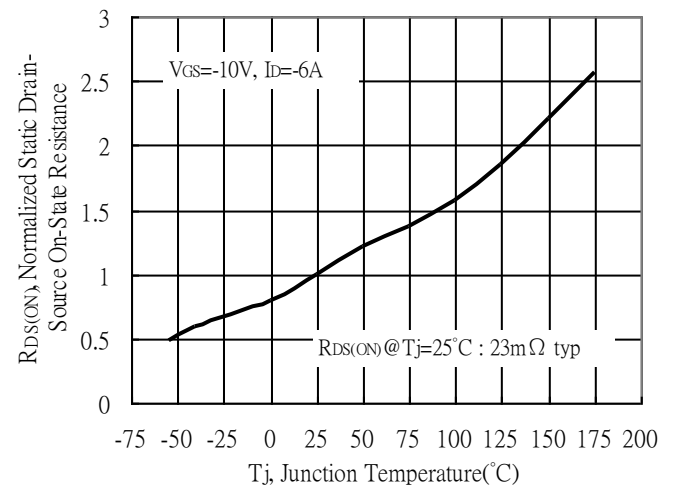
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

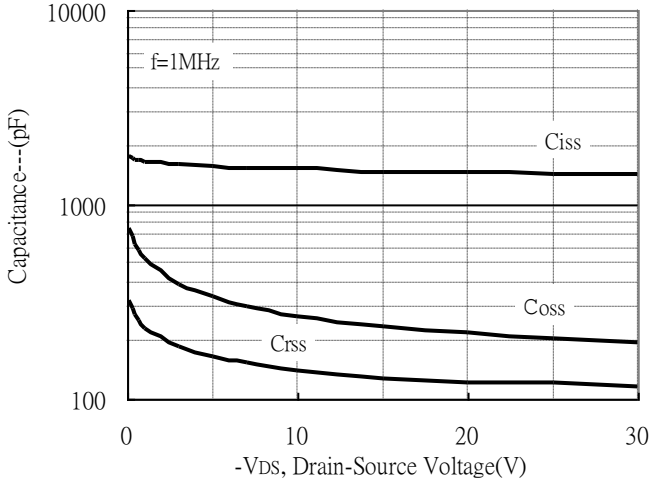


Drain-Source On-State Resistance vs Junction Temperature

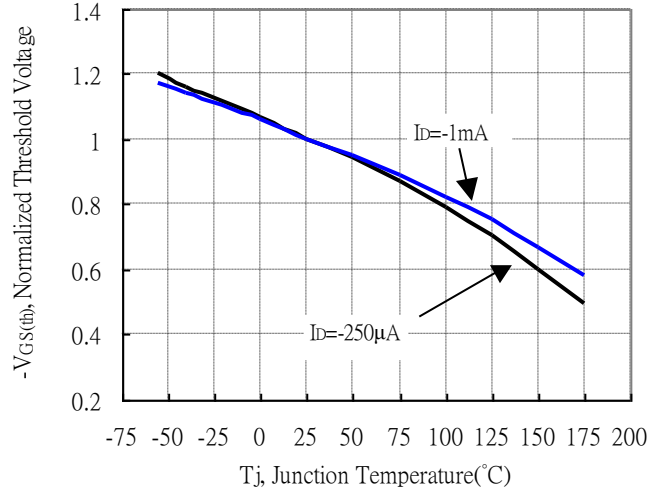


**Typical Characteristics (Cont.)**

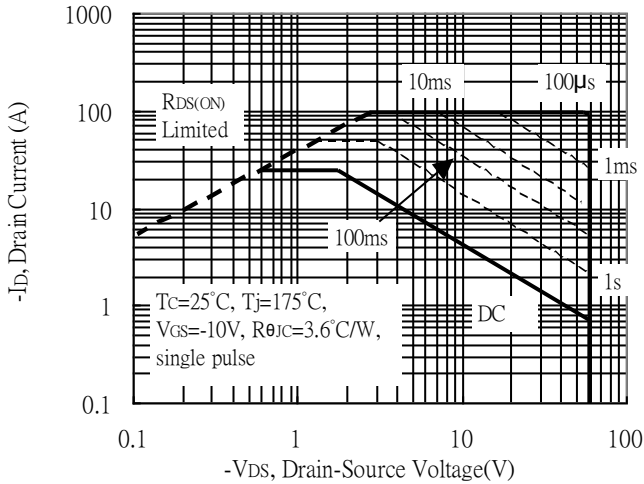
Capacitance vs Drain-to-Source Voltage



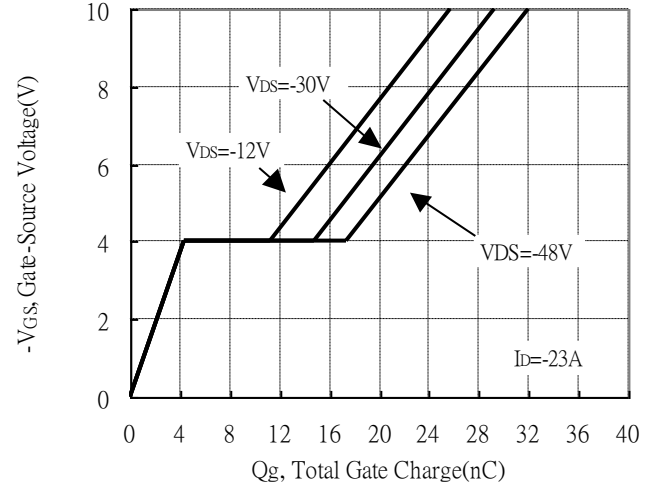
Threshold Voltage vs Junction Temperature



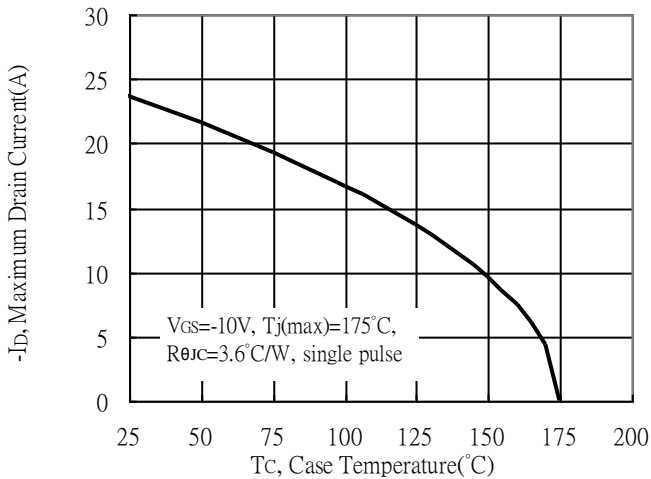
Maximum Safe Operating Area



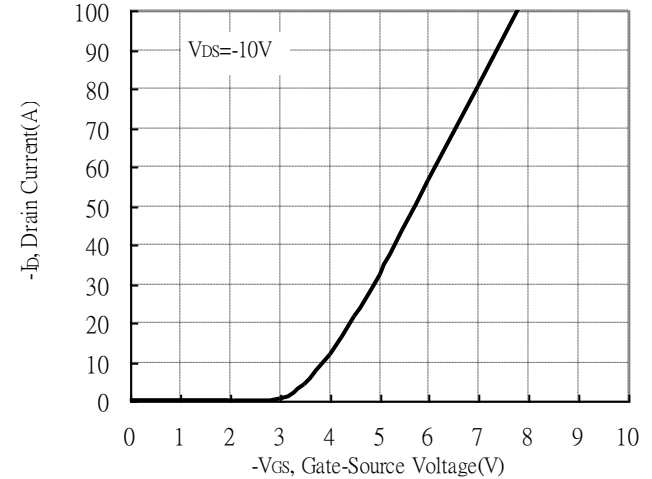
Gate Charge Characteristics



Maximum Drain Current vs Case Temperature



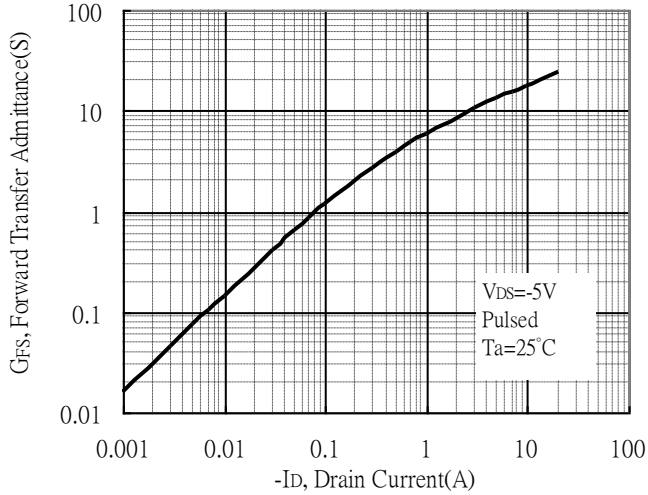
Typical Transfer Characteristics



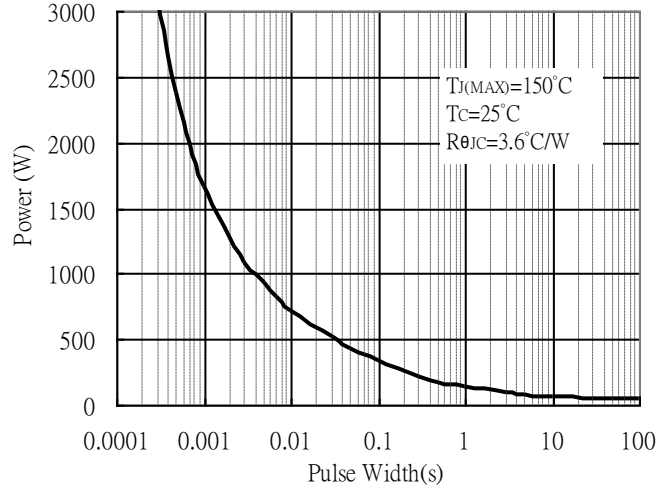


### Typical Characteristics (Cont.)

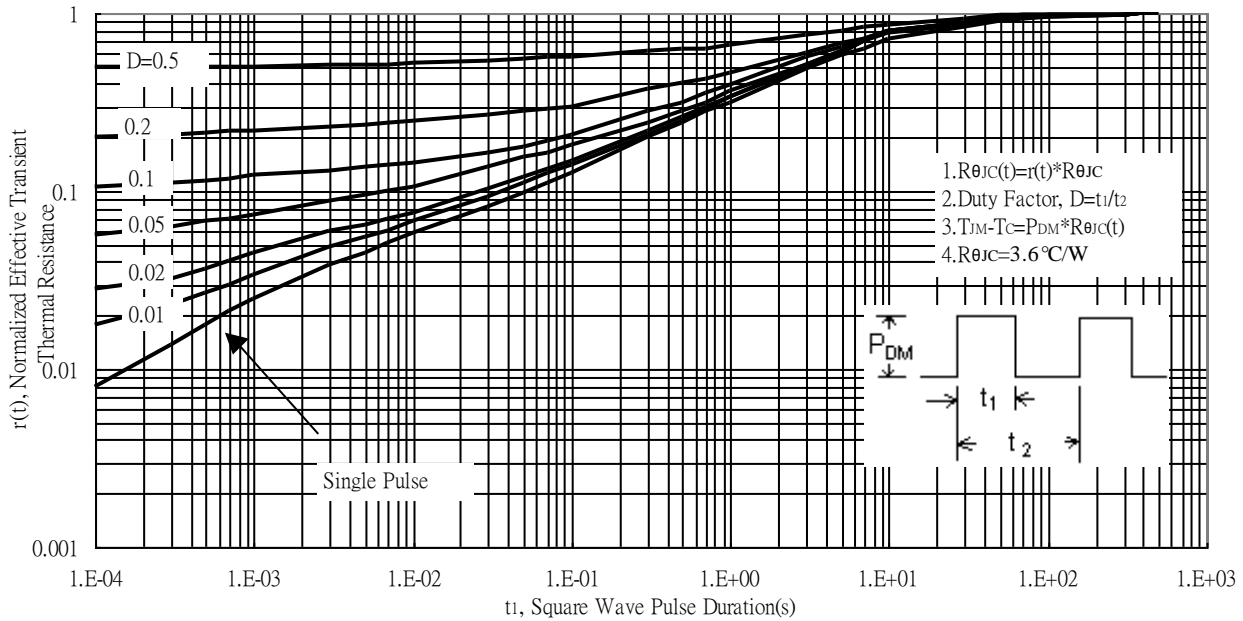
Forward Transfer Admittance vs Drain Current



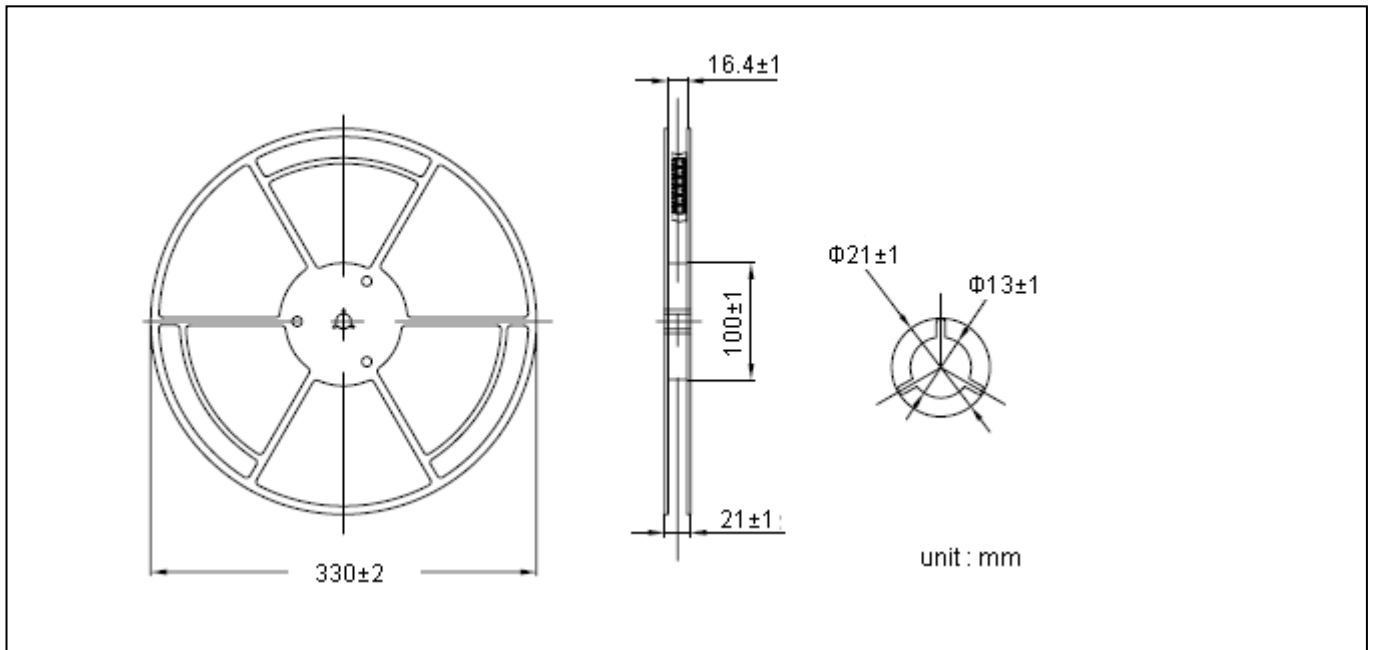
Single Pulse Power Rating, Junction to Case



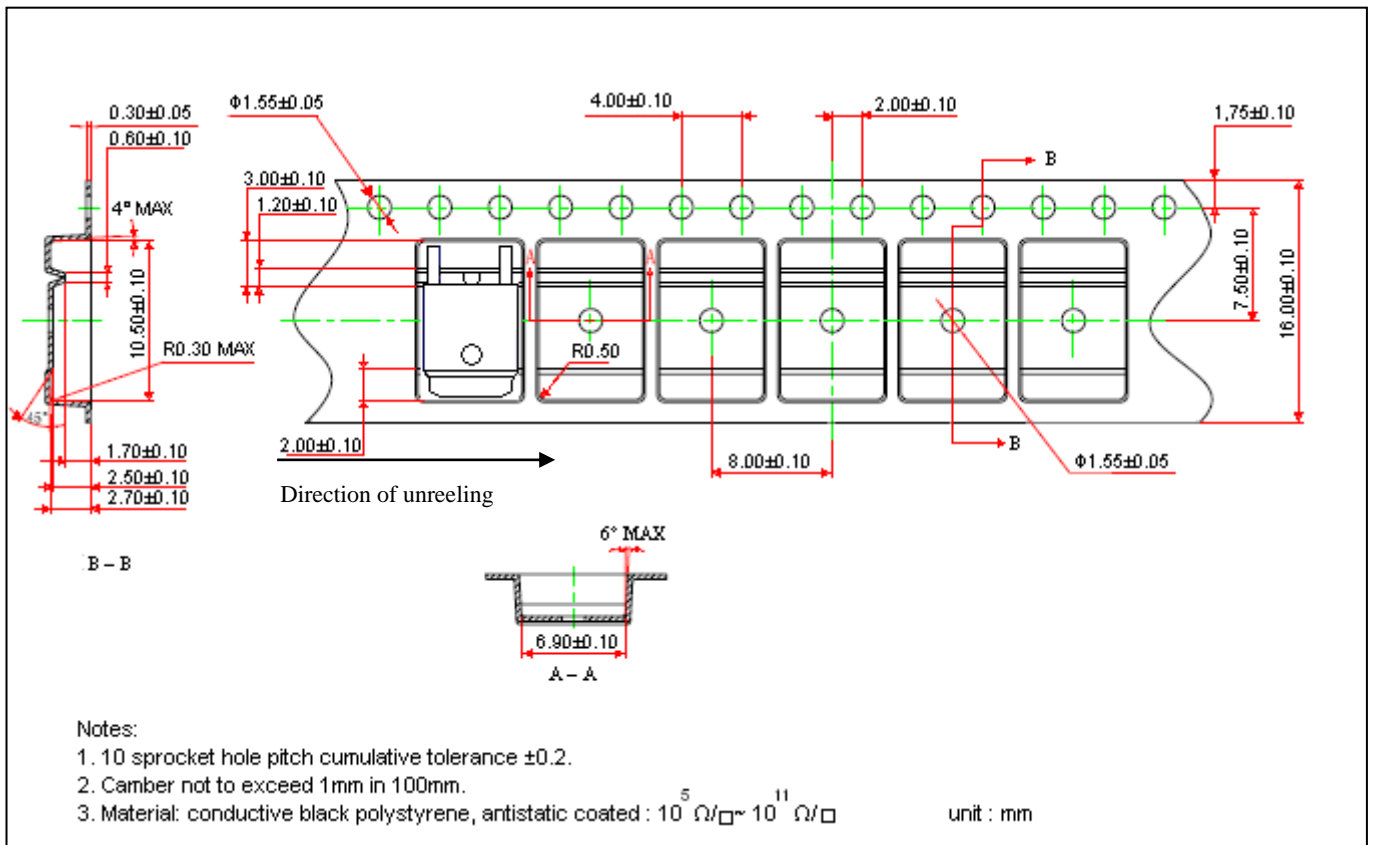
Transient Thermal Response Curves



### Reel Dimension



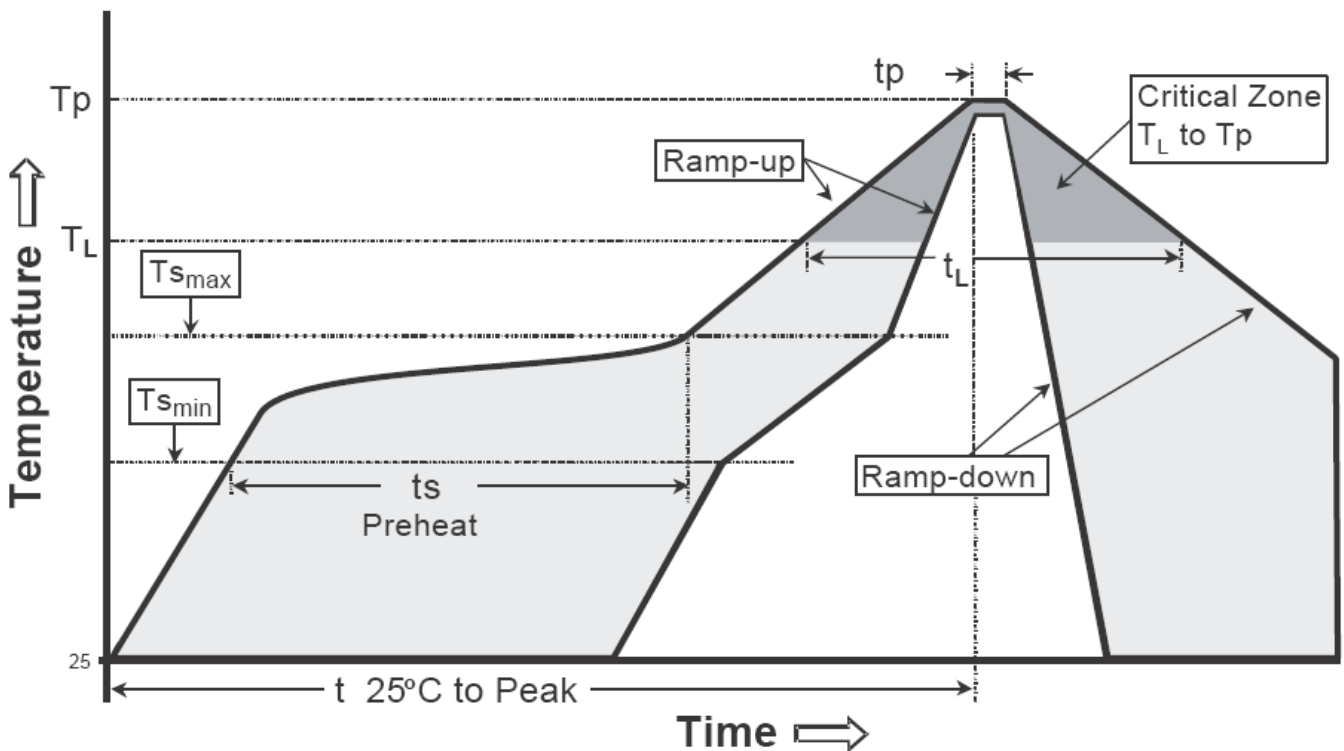
### Carrier Tape Dimension



**Recommended wave soldering condition**

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

**Recommended temperature profile for IR reflow**

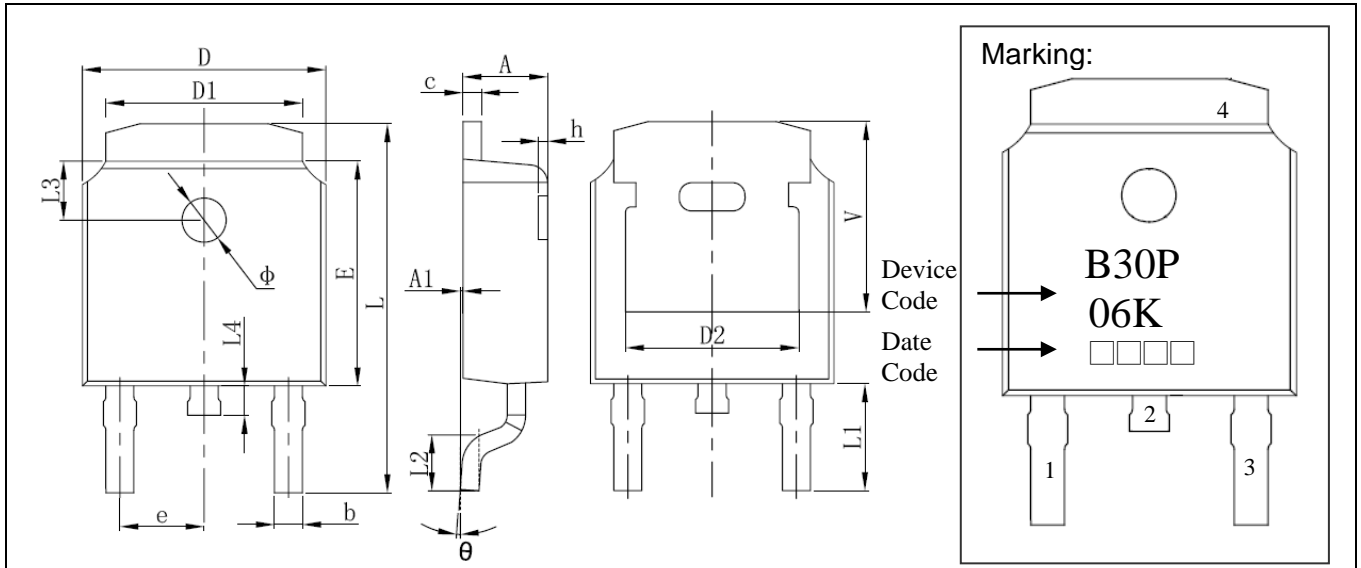


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (TL)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.



**TO-252 Dimension**



**3-Lead TO-252 Plastic Surface Mount Package**  
 CYStek Package Code: J3

Style: Pin 1.Gate 2.Drain 3.Source 4.Drain

Date Code :  
 First Code : Last digit of Christian Year  
 Second Code : Month Code : Jan→A, Feb→B, Mar→C, Apr→D, May→E, Jun→F, Jul→G,  
 Aug→H, Sep→J, Oct→K, Nov→L, Dec→M  
 Last Two Codes : Production Serial Code, 01~99

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	L	0.382	0.406	9.712	10.312
A1	0.000	0.005	0.000	0.127	L1	0.114	REF	2.900	REF
b	0.025	0.030	0.635	0.770	L2	0.055	0.067	1.400	1.700
c	0.018	0.023	0.460	0.580	L3	0.063	REF	1.600	REF
D	0.256	0.264	6.500	6.700	L4	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	Φ	0.043	0.051	1.100	1.300
D2	0.190	REF	4.830	REF	θ	0°	8°	0°	8°
E	0.236	0.244	6.000	6.200	h	0.000	0.012	0.000	0.300
e	0.086	0.094	2.186	2.386	v	0.207	REF	5.250	REF

Notes: 1.Controlling dimension: millimeters.  
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

**Material:**

- Lead : Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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